

# ZXTP25020DFH

## 20V, SOT23, PNP medium power transistor

### Summary

$BV_{CEO} > -20V$

$BV_{ECO} > -4V$

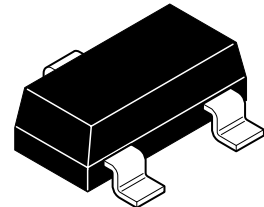
$I_{C(cont)} = 4A$

$V_{CE(sat)} < 60\text{ mV @ } 1A$

$R_{CE(sat)} = 39\text{ m}\Omega$

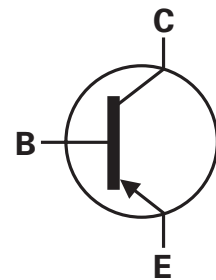
$P_D = 1.25W$

Complementary part number ZXTN25020DFH



### Description

Advanced process capability and package design have been used to maximize the power handling and performance of this small outline transistor. The compact size and ratings of this device make it ideally suited to applications where space is at a premium.

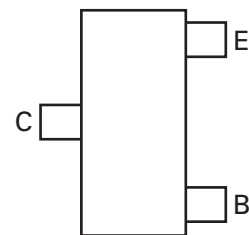


### Features

- High power dissipation SOT23 package
- High peak current
- High gain
- Low saturation voltage

### Applications

- MOSFET gate drivers
- Power switches
- Motor control



Pinout - top view

### Ordering information

Device	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTP25020DFHTA	7	8	3000

### Device marking

1A3

# ZXTP25020DFH

## Absolute maximum ratings

Parameter	Symbol	Limit	Unit
Collector-base voltage	$V_{CBO}$	-25	V
Collector-emitter voltage (forward blocking)	$V_{CEO}$	-20	V
Emitter-collector voltage (reverse blocking)	$V_{ECO}$	-4	V
Emitter-base voltage	$V_{EBO}$	-7	V
Continuous collector current <sup>(c)</sup>	$I_C$	-4	A
Base current	$I_B$	-1	A
Peak pulse current	$I_{CM}$	-10	A
Power dissipation at $T_{amb} = 25^\circ\text{C}^{(a)}$	$P_D$	0.73	W
Linear derating factor		5.84	mW/°C
Power dissipation at $T_{amb} = 25^\circ\text{C}^{(b)}$	$P_D$	1.05	W
Linear derating factor		8.4	mW/°C
Power dissipation at $T_{amb} = 25^\circ\text{C}^{(c)}$	$P_D$	1.25	W
Linear derating factor		9.6	mW/°C
Power dissipation at $T_{amb} = 25^\circ\text{C}^{(d)}$	$P_D$	1.81	W
Linear derating factor		14.5	mW/°C
Operating and storage temperature range	$T_j, T_{stg}$	-55 to 150	°C

## Thermal resistance

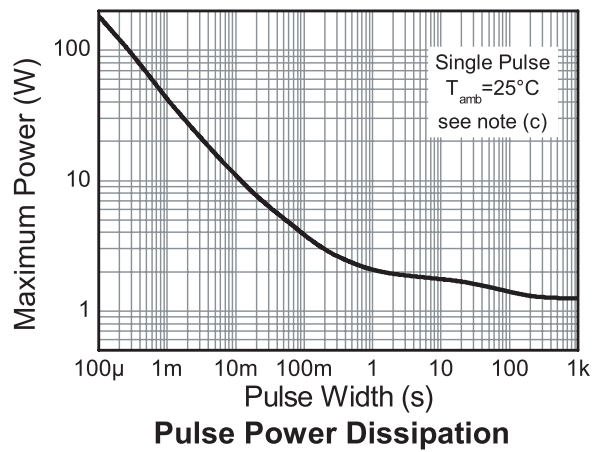
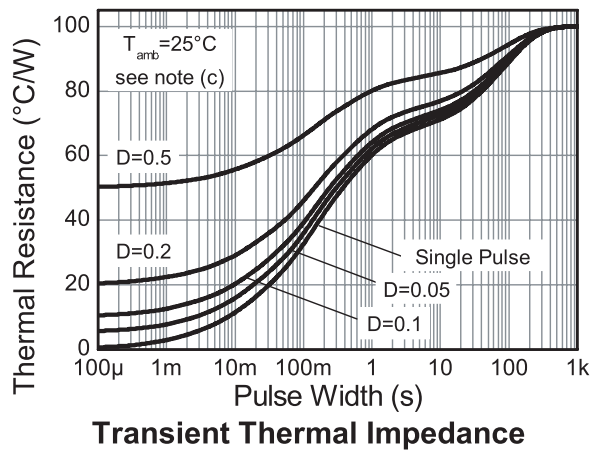
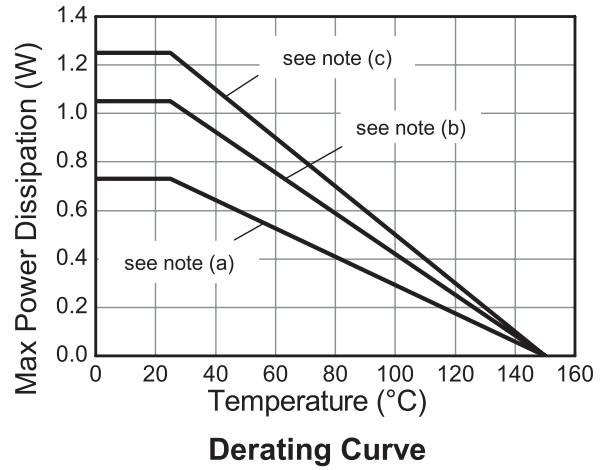
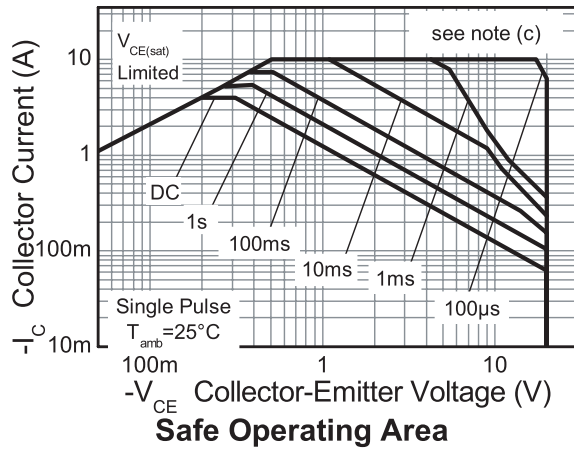
Parameter	Symbol	Limit	Unit
Junction to ambient <sup>(a)</sup>	$R_{\theta JA}$	171	°C/W
Junction to ambient <sup>(b)</sup>	$R_{\theta JA}$	119	°C/W
Junction to ambient <sup>(c)</sup>	$R_{\theta JA}$	100	°C/W
Junction to ambient <sup>(d)</sup>	$R_{\theta JA}$	69	°C/W

### NOTES:

- (a) For a device surface mounted on 15mm x 15mm x 0.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
- (b) For a device surface mounted on 25mm x 25mm x 0.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
- (c) For a device surface mounted on 50mm x 50mm x 0.6mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions.
- (d) As (c) above measured at  $t < 5$  seconds.

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## Characteristics



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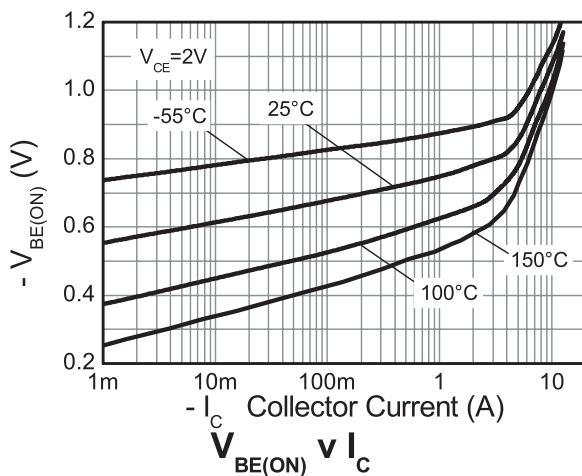
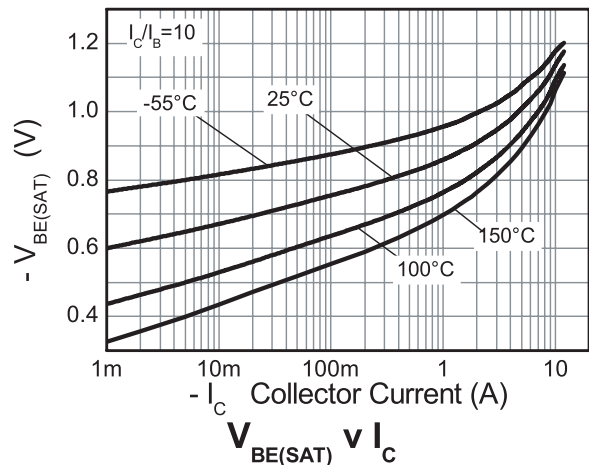
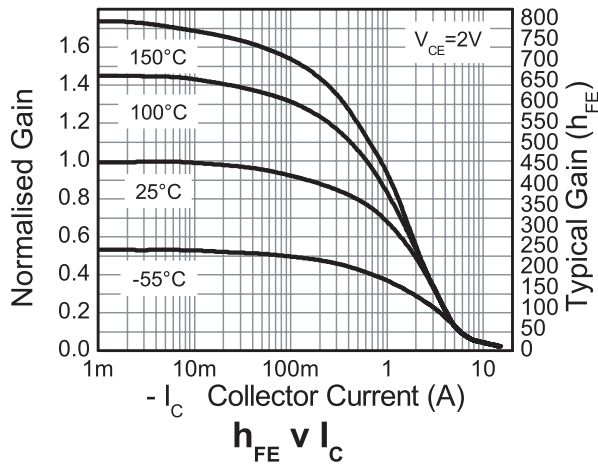
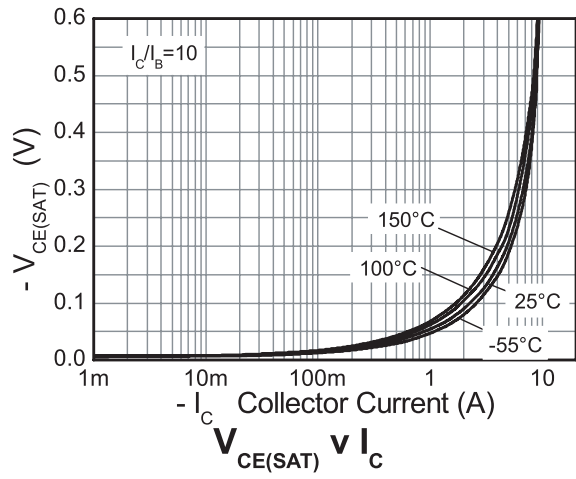
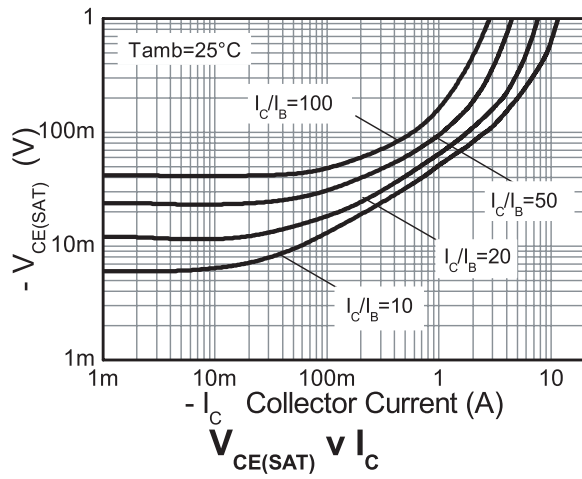
## Electrical characteristics (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Collector-base breakdown voltage	$BV_{CBO}$	-25	-55		V	$I_C = -100\mu\text{A}$
Collector-emitter breakdown voltage (base open)	$BV_{CEO}$	-20	-45		V	$I_C = -10\text{mA}^{(*)}$
Emitter-base breakdown voltage	$BV_{EBO}$	-7	-8.3		V	$I_E = -100\mu\text{A}$
Emitter-collector breakdown voltage (reverse blocking)	$BV_{ECO}$	-4	-8.5		V	$I_C = -100\mu\text{A}^{(*)}$
Collector cut-off current	$I_{CBO}$		<-1	-50	nA	$V_{CB} = -20\text{V}$
				-20	$\mu\text{A}$	$V_{CB} = -20\text{V}, T_{amb} = 100^{\circ}\text{C}$
Emitter cut-off current	$I_{EBO}$		<-1	-50	nA	$V_{EB} = -5.6\text{V}$
Collector-emitter saturation voltage	$V_{CE(sat)}$		-50	-60	mV	$I_C = -1\text{A}, I_B = -100\text{mA}^{(*)}$
			-150	-210	mV	$I_C = -1\text{A}, I_B = -10\text{mA}^{(*)}$
			-180	-240	mV	$I_C = -2\text{A}, I_B = -40\text{mA}^{(*)}$
			-155	-180	mV	$I_C = -4\text{A}, I_B = -400\text{mA}^{(*)}$
Base-emitter saturation voltage	$V_{BE(sat)}$		-960	-1050	mV	$I_C = -4\text{A}, I_B = -400\text{mA}^{(*)}$
Base-emitter turn-on voltage	$V_{BE(on)}$		-815	-900	mV	$I_C = -4\text{A}, V_{CE} = -2\text{V}^{(*)}$
Static forward current transfer ratio	$h_{FE}$	300	450	900		$I_C = -10\text{mA}, V_{CE} = -2\text{V}^{(*)}$
		200	310			$I_C = -1\text{A}, V_{CE} = -2\text{V}^{(*)}$
		70	100			$I_C = -4\text{A}, V_{CE} = -2\text{V}^{(*)}$
			20			$I_C = -10\text{A}, V_{CE} = -2\text{V}^{(*)}$
Transition frequency	$f_T$		290		MHz	$I_C = -50\text{mA}, V_{CE} = -10\text{V}$ $f = 50\text{MHz}$
Output capacitance	$C_{OBO}$		21	30	pF	$V_{CB} = -10\text{V}, f = 1\text{MHz}^{(*)}$
Delay time	$t_{(d)}$		14.2			$V_{CC} = -10\text{V}, I_C = -1\text{A}, I_{B1} = I_{B2} = -50\text{mA}.$
Rise time	$t_{(r)}$		16.3			
Storage time	$t_{(s)}$		186			
Fall time	$t_{(f)}$		32.7			

### NOTES:

(\*) Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

## Typical characteristics



# ZXTP25020DFH

## Package outline - SOT23



Dim.	Millimeters		Inches		Dim.	Millimeters		Inches	
	Min.	Max.	Min.	Max.		Min.	Max.	Max.	Max.
A	2.67	3.05	0.105	0.120	H	0.33	0.51	0.013	0.020
B	1.20	1.40	0.047	0.055	K	0.01	0.10	0.0004	0.004
C	-	1.10	-	0.043	L	2.10	2.50	0.083	0.0985
D	0.37	0.53	0.015	0.021	M	0.45	0.64	0.018	0.025
F	0.085	0.15	0.0034	0.0059	N	0.95 NOM		0.0375 NOM	
G	1.90 NOM		0.075 NOM		-	-	-	-	-

**Note:** Controlling dimensions are in millimeters. Approximate dimensions are provided in inches

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